

Osptek Display

TFT LCD SPECIFICATION

Model No:

YDP180BT006-V10

osptek[®]

REVISION RECORD

REV NO. 版 本	CONTENTS 内 容	REVISION ITEM 修改项目	REV DATE 日 期
V1.0	First release	Preliminary	2024-01-24
V1.1	Update	优化TFPC外形+更换为胶铁高色域背光	2024-06-17

CONTENTS

1. GENERAL SPECIFICATIONS(主要特征描述)	P.3
2. EXTERNAL DIMENSIONS(外形尺寸)	P.4
3. ABSOLUTE MAXIMUM RATINGS(极限参数).....	P.5
4. ELECTRICAL CHARACTERISTICS(模块电气特性).....	P.5
5. BACKLIGHT SPECIFICATION(背光电气特性).....	P.5
6. ELECTRO-OPTICAL CHARACTERISTICS(光电参数).....	P.6
7. INTERFACE DESCRIPTION(接口定义描述).....	P.7
8. TIMING CHARACTERIST(时序特征).....	P.7
9. RELIABILITY TEST CONDITIONS(可靠性实验条件).....	P.8
10. INSPECTION CRITERION(检查标准)(参考REX-IIS)	P.9
11.PRECAUTIONS FOR USING LCD MODULES(使用注意事项).....	P.9
12. PRIOR CONSULT MATTER (提前商议事项)	P.10

1. GENERAL SPECIFICATIONS(主要特征描述)

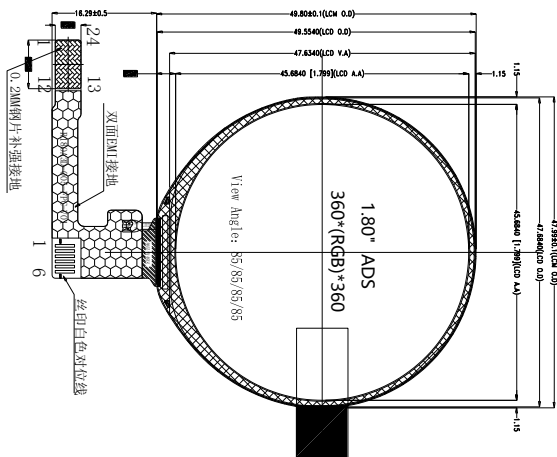
Item 项目	Contents 内容	Unit 单位
LCD type 液晶显示类型	262K Colors TFT TRANSMISSIVE	/
Diagonal length 尺寸	1.80	inch
Recommended Viewing Direction 推荐使用方向	ALL	0' Clock
Dot arrangement 点阵	360*3(R.G.B)*360	Dot
Assembly size (W*H*T) 总成尺寸 (宽*高*厚)	49.34*49.34*4.17	mm ³
Module size (W*H*T) 模块外围尺寸 (宽*高*厚)	47.99*49.80*1.54	mm ³
Viewing area (W*H) 可视区域 (宽*高)	45.40*45.40	mm ²
Active area (W*H) 有效显示区域 (宽*高)	45.68*45.68	mm ²
Pixel size (W*H) 像素大小 (宽*高)	0.1269*0.1269	mm ²
Backlight Type 背光类型	LED(white 4*LED)	/
Drive IC 驱动 IC	ST77916	/
Interface Type 接口类型	QSPI	/

osptek®

2 EXTERNAL DIMENSIONS(外形尺寸)

1		2		3		4		5		6		7		8		9		10	
有害物质管理标准																			
☒ 依照RoHS环保指令 ☐ 依照RoHS环保指令+无卤素要求																			
A		☐		有害物质管理标准 第 二 版															
REV		Date		Description															
V01		202.40108		NEW															
V02		202.40530		优化TPC外形+换胶铁背光															
A																			

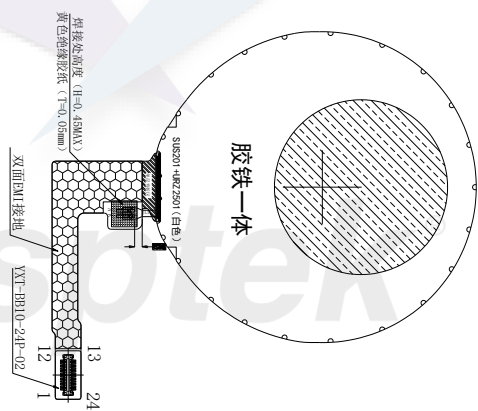
正视图



側视图



背视图



1	CTP-SCL
2	CTP-SDA
3	CTP-RST
4	CTP-INT
5	CTP-VDD 3.3V
6	GND

TP定义

QSPI

No.	SYMBOL
1	LEDA
2	LEIK
3	GND
4	CTP SCL
5	CTP SDA
6	CTP RST
7	CTP INT
8	GND
9	CTP VDD3, 3V
10	VDD3, 3V
11	GND
12	ICD RST
13	TE
14	NC
15	GND
16	QSP1 S103
17	GND
18	QSP1 S102
19	GND
20	NC
21	QSP1 LSCK
22	QSP1 S101
23	QSP1 S100
24	CS

FPC 展开出货

QSPI

$I_F=60\text{ mA}$ $V_F=2.8\text{ V}\sim 3.4\text{ V}$

背光灯电路图

- 1) Display mode: 1.80" 360x360 262K Colors IPS
- 2) Viewing angle: ALL
- 3) Operating temp.: -20°C ~ +60°C
Storage temp.: -20°C ~ +70°C
- 4) IC: S177916
- 5) Backlight: 3 chip White LED
1 LED = 00mA V LED = 2.8V ~ 3.4V 0.6珠 + 1蓝色域
- 6) General Tolerance: ±0.20.
- 7) Rols Compliance.
- 8) Recommended Case Open Area should be refer to the drawing.

MATERIAL	FINISH	深圳市鱼鹰光电科技有限公司					
	※ SURFACE FINISH	Shenzhen Osprey Optoelectronics Technology Co., Ltd.					
	※ SURFACE DIMENSION						
APPROVED		TITLE	LCM	SIZE	SHEET NUMBER	REVISION	
CHECKED		PRO. NO.	YDPI080T006-V1.0	A4	1 of 1	1	
DESIGNED	WCP	DWG. NO.		9-4 ANGLE	SCALE: 1:1		

3. ABSOLUTE MAXIMUM RATINGS(极限参数)

Parameter 参数	Symbol 符号	Min 最小值	Max 最大值	Unit 单位	Remark 备注
Operating temperature 操作温度	Top	-20	70	°C	At 25 ±5°C
Storage temperature 储存温度	Tst	-30	80	°C	
Humidity 湿度	RH	/	90%(Max60°C)	RH	
Power Voltage 电源电压	VDD	-0.3	4.6	V	
	VDDIO	-0.3	4.6	V	

4. ELECTRICAL CHARACTERISTICS(模块电气特性)

Parameter 参数	Symbol 符号	Min 最小值	Typ 典型	Max 最大值	Unit 单位
Supply voltage for logic 逻辑电压	VDD	2.5	2.8	3.3	V
I/O power supply I/O 口电压	VDDIO	1.65	2.8	3.3	V
Input Current 输入电流	Nomal Mode IOVCC+VDD	-			mA
	Sleep Mode IOVCC+VDD	-			uA
Input voltage 'H' level 输入高电平	V _{IH}	0.7*VDDIO	-	VDDIO	V
Input voltage 'L' level 输入低电平	V _{IL}	0	-	0.3*VDDIO	V
Output voltage 'H' level 输出高电平	V _{OH}	0.8*VDDIO	-	VDDIO	V
Output voltage 'L' level 输出低电平	V _{OL}	0	-	0.2*VDDIO	V

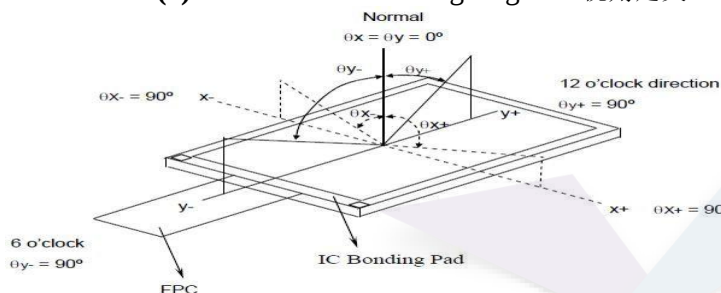
5. BACKLIGHT SPECIFICATION(背光电气特性)

Item 项目	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Condition 条件
Forward voltage 正向电压	V _f	2.8	3.0	3.3	V	I _f = 60mA
Backlight uniformity 均匀度	No less than 80% (不低于 80%)					
Number of LED LED 数量	-	3			Piece	
Connection mode 连接模式	S/P/M	并联			-	

6. ELECTRO-OPTICAL CHARACTERISTICS(光电参数)

Item 项目	Symbol 符号	Condition 条件	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Note 备注
LCM Surface Luminance 模组表面亮度	Lv	--		400		cd/m ²	Note 4
Contrast Ratio 对比度	CR	--	800	1200		--	Note 2
Response time 响应时间	Tr+Tf	--		30	35	msec	Note 3
Color gamut 色域	S(%)		65	70		%	
Color chromaticity (CIE 1931) 色彩饱和度	White	X	$\theta=0^\circ$ $\phi=0^\circ$ $T_a=25^\circ\text{C}$	TBD			Note 4 Note 5
		Y		TBD			
	Red	X		TBD			
		Y		TBD			
	Green	X		TBD			
		Y		TBD			
Viewing angle 视角范围	Ver.	X-	80	85		deg	Note 1
		Y-	80	85			
	Hor.	X+	80	85			
		Y+	80	85			

Note (1): Definition of Viewing Angle (视角定义)

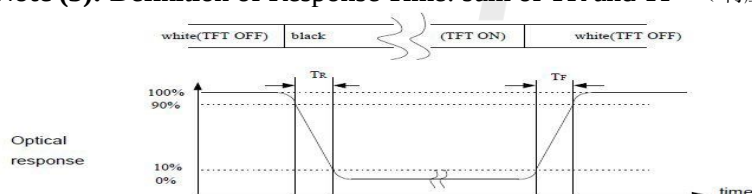


Note (2): Definition of Contrast Ratio(CR) (对比度定义)

Measured point 1 through 5 of panel. (测试 P1 到 P5 的亮度)

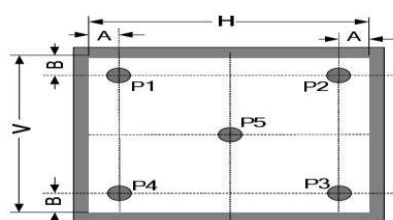
$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}} = \frac{\text{显示白色画面时平均表面亮度}}{\text{显示黑色画面时平均表面亮度}}$$

Note (3): Definition of Response Time: sum of TR and TF (响应时间定义)



Note (4): Measuring method for Contrast ratio, Surface Luminance, Luminance uniformity, CIE(x,y) Chromaticity (对比度, 表面亮度, 均匀度, CIE 坐标测试方法)

A : 5 mm
B : 5 mm
H, V : Active Area
Light spot size $\phi=5\text{mm}$, 500mm distance from the LCD surface to detector lens
measurement instrument is TOPCON's luminance meter BM-7



Note (5): CIE(x,y) Chromaticity, The X,Y value is determined by screen active area position 5. (CIE 坐标测试测试点为显示屏中心点 P5)

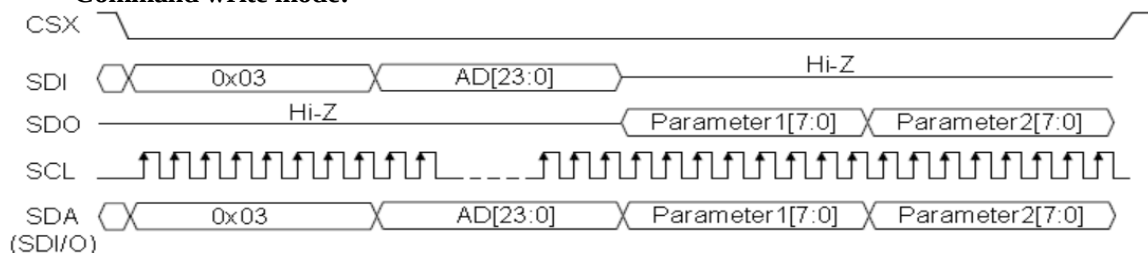
7. INTERFACE DESCRIPTION(接口定义描述)

Pin No. Pin序	Symbol 符 号	I/O 输入/出	Description 描 述	Memo 备注
1	LEDA	P	Power supply Anode input for backlight	
2	LEDK	P	Power supply Cathode input for backlight	
3	GND	P	Ground	
4	CTP_SCL	I	CTP Interface I2C CLOCK Pin	
5	CTP_SDA	I/O	CTP Interface I2C Data Pin	
6	CTP_RESET	I	This signal will reset Touch IC,Signal is active low	
7	CTP_INT	O	CTP I2C interrupt to Host	
8	GND	P	Ground	
9	CTP-VDD3.3	P	Power supply for CTP internal Analog	
10	VDD/IOVCC	P	Power supply to the internal Analog	
11	GND	P	Ground	
12	RESET	I	Reset signal pin	
13	TE	O	Frame head pulse signal	
14	NC	/	NC	
15	GND	P	Ground	
16	SI03	I	Serial Data input pin 3	
17	GND	P	Ground	
18	SI02	I	Serial Data input pin 2	
19	GND	P	Ground	
20	NC	/	NC	
21	CLK	I	Serial Clock signal	
22	SI01	I	Serial Data input pin 1	
23	SI00=SDA	IO	Serial Data input/output pin 0	
24	CS	I	Chip selection pin	

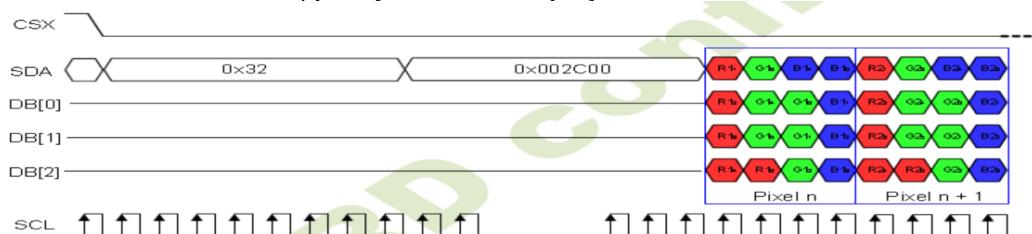
8. TIMING CHARACTERIST (时序特征)

8.1 AC Elerical Characteristics 模拟电气特性

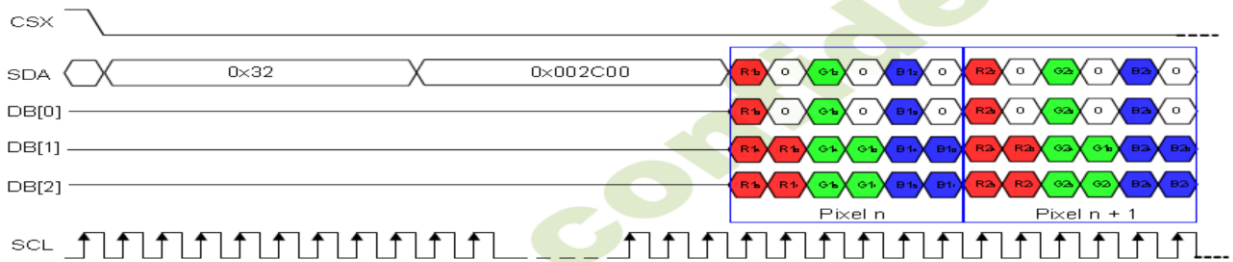
Command write mode:



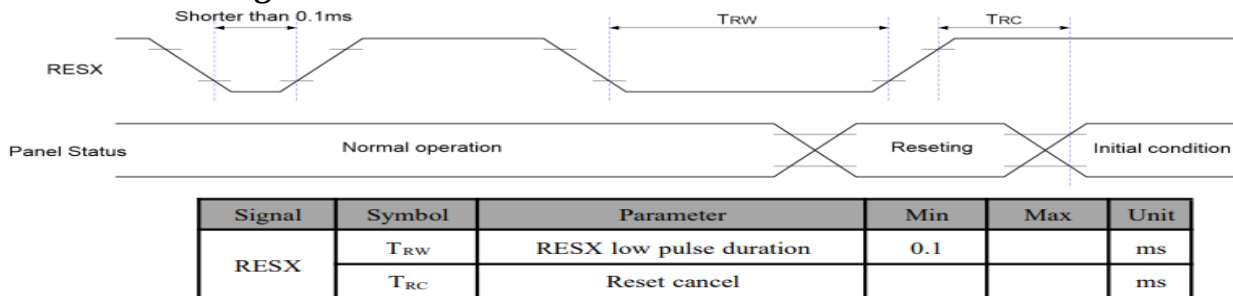
Write data for 16-bit/pixel(RGB 565 bit input), 65K Colors, 3AH='05h'



Write data for 18-bit/pixel(RGB 666 bit input), 262K Colors, 3AH='06h'



8.2 Reset timing 复位时间



Other information Reference IC datasheet. (ST77916)

9. ELIABILITY TEST CONDITIONS(可靠性实验条件)

NO. 序号	Test Item 实验项目	Test Condition 实验条件	Inspection after test 判定标准
1	High Temperature Storage 高温存放	$70 \pm 2^{\circ}\text{C}$, 200 hours	Inspection after 2~4 hours storage at room temperature, the sample shall be freefrom defects. (试验结束后须正常室温存放 2~4 个小时之后才能测试判定, 不允许有以下缺陷) 1. Air bubble in the LCD (模块中有气泡); 2. Seal leak (漏液); 3. Non-display (不显示); 4. Missing segments(漏笔); 5. Glass crack (玻璃破碎); 6. Current IDD is twice higher than initial value (电流 Idd 大于初时值的 2 倍); 7. The surface damage (表面损伤); 8. Do not meet the electrical characteristics (不满足模块电气性能);
2	Low Temperature Storage 低温存放	$-30 \pm 2^{\circ}\text{C}$, 200 hours	
3	High Temperature Operating 高温操作	$60 \pm 2^{\circ}\text{C}$, 120 hours	
4	Low Temperature Operating 低温操作	$-20 \pm 2^{\circ}\text{C}$, 120 hours	
5	Damp proof Test Storage 高温高湿存放	$40 \pm 2^{\circ}\text{C}$, 90%RH, 120 hours	
6	Temperature Cycle Storage 冷热循环存放	$-20 \pm 2^{\circ}\text{C}$ (30min) ~ 25°C (5min) ~ $70 \pm 2^{\circ}\text{C}$ (30min), 10Cycle.	
7	Vibration Test 振荡试验	Frequency(频率):10HZ-55Hz , Amplitude(振幅):1.5mm , X, Y, Z every direction for 1 hour (Packing condition) (包装状态, X, Y, Z 每个方向各 1 小时)	
8	Dropping Test 跌落试验	Drop to the ground from 1M height, one time, every side of carton (Packing condition) (包装状态, 一米高度, 6 面各一次)	

9	ESD Test 静电测试	C:150pf; R:330Ω; Voltage:8KV; Air discharge(空气放电),10 time Voltage:4KV; Connet discharge(接触放电),10 time	
Remark (备注): 1. The samples should be applied to only on test item(每个被测试样品只能用于其中的一个测试项目); 2. Sample size for each test item is 5~10 pcs(每个测试项目的样品数量为5~10片); 3. For Damp Proof Test, Pure water(Resistance>10M Ω) should be used (对于防潮试验, 试验箱的用水必须是电阻大于10M 欧姆的纯水); 4. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting ,it would be judged as a good part (如果由静电引起产品故障, 当放置一段时间后能够恢复正常, 则不视为产品缺陷); 5. Failure Judgment Criterion: Basic Specification ,Electrical Characteristic, mechanical Characteristic, Optical Characteristic (故障判断标准: 基本规格, 电气特性, 机械特性, 光电特性).			

10.INSPECTION CRITERION(检查标准)(参考REX-BZ-001)

11.PRECAUTIONS FOR USING LCD MODULES(使用注意事项)

11.1 Using LCD Modules 使用

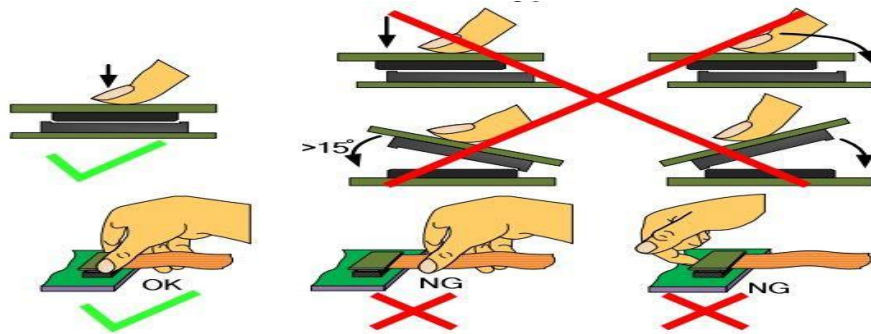
- 11.1.1 As glass is fragile, It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact. (由于玻璃是脆的, 使用过程请特别注意边缘区, 防止跌落或振动, 不能机械碰撞)。
- 11.1.2 Do not apply excessive force to the display surface or the adjoining are since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals(some cosmetics are determined to the polarizer) (请勿施加过大的压力于显示屏或连接部位, 否则会引起色调变化。不要裸手接触显示屏, 这将弄脏显示区和降低端子之间的绝缘能力。一些外观问题是由偏光片决定的)。
- 11.1.3 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizes with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air. (覆盖液晶显示模块显示平面的偏光片是软性且易被擦伤, 请小心轻拿。请勿用任何硬度大于HB 铅笔芯的物品(玻璃, 镊子等) 接触、撞压或摩擦裸露偏光片不要放置或粘附物体在显示区域上以免留下痕迹。冷凝在表面和端子将会损坏或弄脏偏光片。产品在 低温下测试之后, 与室温空气接触之前必须在容器内升温)
- 11.1.4 If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents: Isopropyl alcohol; Ethyl alcohol . Do not scrub hard to avoid damaging the display surface(如果显示平面受污, 可对平面吹热气且轻轻地用软性干布擦除。如果受污严重, 用含下列一种溶剂的湿布擦除:甘油, 酒精 。请勿用力擦拭以免损坏显示平面。)
- 11.1.5 Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following: Water, Ketone, Aromatic solvents. Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats. (除以上提到的溶剂外, 其他溶剂可能会损坏偏光片, 特别要避免使用以下溶剂: 水, 丙酮, 芳烃溶剂。立即擦掉唾液或水滴, 长时间与水接触会引起变形或褪色。避免接触油和油脂)
- 11.1.6 Do not attempt to disassemble or process the LCD module. (请勿拆卸液晶显示模块)
- 11.1.7 Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment. (由于液晶显示模块使用 CMOS 集成, 要特别注意静电放电问题。对 CMOS器件, 要特别注意静电。为防止静电损坏, 注意保持合宜的工作环境)
- 11.1.8 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative

voltage becomes stable. (开机时, 先让逻辑电压, 再接通模拟高压, 如显示屏驱动电压。关机时, 先断开模拟高压, 再关逻辑电压。正负电源都稳定后再送控制信号。)

11.1.9 In the use of connector products, the operating process of attention to turn off the power before pull off and insert action. To avoid damage to the module (在使用连接器的产品时, 插接过程注意先关闭电源再进行拔插动作, 避免损坏模块)

11.1.10 Precaution for assemble the module with BTB connector: Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows

(用板对板连接器安装液晶显示模块注意事项: 请注意连接器的公母及连接位置, 请勿出现下图所示的错误连接方式)



11.2 Storage Modules 储存

11.2.1 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0° C and 35° C, and keep the relative humidity between 40%RH and 60%RH. (避光保存, 避免直接暴露在太阳光或黄光灯下, 保持温度在 0~35 摄氏度之间, 保持相对湿度在 40%RH 和 60%RH 之间。)

11.2.2 The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped). (偏光片表面避免接触其他物质, 建议存放在货运防静电包装中)

11.3 Soldering

11.3.1 Iron head temperature (烙铁头实际温度): 350±10°C, Soldering time (焊接时间): <3-4S. Soldering don't repeat above 3 times (焊接次数勿超过 3 次)

11.3.2 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the of a non-halogen type of flux). It is recommended that you protect the LCD surface case with a cover during soldering to prevent any damage due to flux spatters. (如果使用助焊剂, 完成焊接后一定要清除剩余的助焊剂 (除非卤化物助焊剂)。建议焊接时用盖子保护显示屏面以避免因焊剂油溅出造成的任何损坏。)

12. PRIOR CONSULT MATTER (提前商议事项)

14.1 For OSP electronics standard products, we keep the right to change material, process ... for improving the product property without prior notice to our customer.

(对于鱼鹰电子的标准模块产品, 我们保留在不通知客户的情况下, 为提高产品性能而改变原材料及加工方法等的权利。)

14.2 If you have special requirement about reliability condition, please let us know before you start the design on our samples.

(如对可靠性条件有特殊要求, 请在模块设计开发前通知我们。)